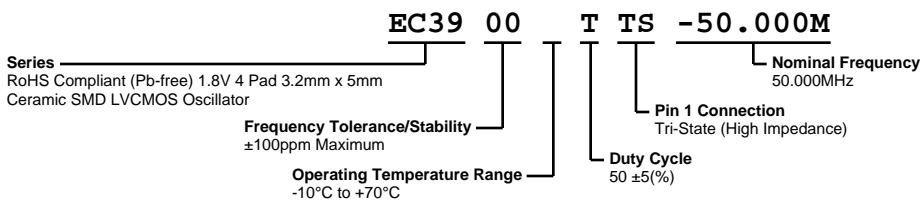


# EC3900TTS-50.000M



**ECLIPTEK**  
CORPORATION



## ELECTRICAL SPECIFICATIONS

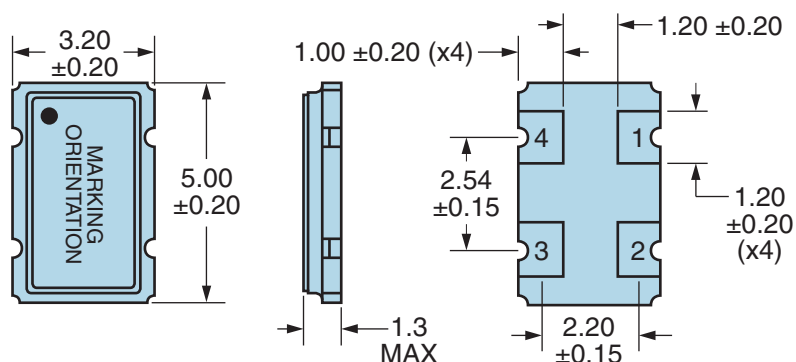
Nominal Frequency	50.000MHz
Frequency Tolerance/Stability	±100ppm Maximum (Inclusive of all conditions: Calibration Tolerance at 25°C, Frequency Stability over the Operating Temperature Range, Supply Voltage Change, Output Load Change, First Year Aging at 25°C, Shock, and Vibration)
Operating Temperature Range	-10°C to +70°C
Supply Voltage	1.8Vdc ±5%
Input Current	8mA Maximum
Output Voltage Logic High (Voh)	90% of Vdd Minimum ((IOH=-4mA))
Output Voltage Logic Low (Vol)	10% of Vdd Maximum ((IOH=+4mA))
Rise/Fall Time	3nSec Maximum (Measured at 20% to 80% of waveform)
Duty Cycle	50 ±5(%) (Measured at 50% of waveform)
Load Drive Capability	15pF Maximum
Output Logic Type	CMOS
Pin 1 Connection	Tri-State (High Impedance)
Tri-State Input Voltage (Vih and Vil)	90% of Vdd Minimum or No Connect to Enable Output, 10% of Vdd Maximum to Disable Output (High Impedance)
Standby Current	10µA Maximum (Disabled Output: High Impedance)
RMS Phase Jitter	1pSec Maximum (12kHz to 20MHz offset frequency)
Start Up Time	10mSec Maximum
Storage Temperature Range	-55°C to +125°C

## ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

ESD Susceptibility	MIL-STD-883, Method 3015, Class 1, HBM: 1500V
Fine Leak Test	MIL-STD-883, Method 1014, Condition A
Flammability	UL94-V0
Gross Leak Test	MIL-STD-883, Method 1014, Condition C
Mechanical Shock	MIL-STD-883, Method 2002, Condition B
Moisture Resistance	MIL-STD-883, Method 1004
Moisture Sensitivity	J-STD-020, MSL 1
Resistance to Soldering Heat	MIL-STD-202, Method 210, Condition K
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003
Temperature Cycling	MIL-STD-883, Method 1010, Condition B
Vibration	MIL-STD-883, Method 2007, Condition A

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## MECHANICAL DIMENSIONS (all dimensions in millimeters)



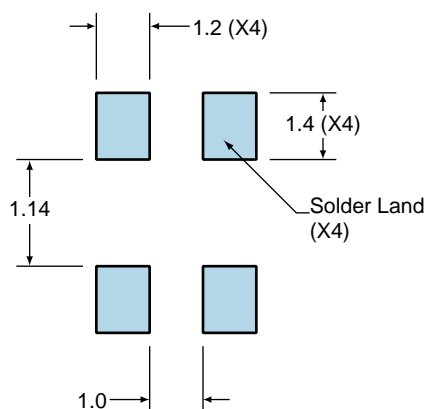
Note: Pin 1 Chamfer not shown.

PIN	CONNECTION
1	Tri-State
2	Ground
3	Output
4	Supply Voltage

LINE	MARKING
1	<b>E50.000</b> <i>E=Ecliptek Designator</i>
2	<b>XXYYZ</b> <i>XX=Ecliptek Manufacturing Code</i> <i>Y=Last Digit of the Year</i> <i>ZZ=Week of the Year</i>

## Suggested Solder Pad Layout

All Dimensions in Millimeters



All Tolerances are  $\pm 0.1$

# EC3900TTS-50.000M

## OUTPUT WAVEFORM & TIMING DIAGRAM



## Test Circuit for CMOS Output



Note 1: An external 0.1 $\mu$ F low frequency tantalum bypass capacitor in parallel with a 0.01 $\mu$ F high frequency ceramic bypass capacitor close to the package ground and  $V_{DD}$  pin is required.

Note 2: A low capacitance (<12pF), 10X attenuation factor, high impedance (>10Mohms), and high bandwidth (>300MHz) passive probe is recommended.

Note 3: Capacitance value  $C_L$  includes sum of all probe and fixture capacitance.

## Recommended Solder Reflow Methods



### High Temperature Infrared/Convection

**Ts MAX to TL (Ramp-up Rate)** 3°C/second Maximum

#### Preheat

- Temperature Minimum (Ts MIN) 150°C  
 - Temperature Typical (Ts TYP) 175°C  
 - Temperature Maximum (Ts MAX) 200°C  
 - Time (ts MIN) 60 - 180 Seconds

**Ramp-up Rate (TL to Tp)** 3°C/second Maximum

#### Time Maintained Above:

- Temperature (TL) 217°C  
 - Time (tL) 60 - 150 Seconds

**Peak Temperature (Tp)** 260°C Maximum for 10 Seconds Maximum

**Target Peak Temperature (Tp Target)** 250°C +0/-5°C

**Time within 5°C of actual peak (tp)** 20 - 40 seconds

**Ramp-down Rate** 6°C/second Maximum

**Time 25°C to Peak Temperature (t)** 8 minutes Maximum

**Moisture Sensitivity Level** Level 1

## Recommended Solder Reflow Methods



### Low Temperature Infrared/Convection 240°C

**T<sub>S</sub> MAX to T<sub>L</sub> (Ramp-up Rate)** 5°C/second Maximum

#### Preheat

- Temperature Minimum (T<sub>S</sub> MIN) N/A  
 - Temperature Typical (T<sub>S</sub> TYP) 150°C  
 - Temperature Maximum (T<sub>S</sub> MAX) N/A  
 - Time (t<sub>S</sub> MIN) 60 - 120 Seconds

**Ramp-up Rate (T<sub>L</sub> to T<sub>P</sub>)** 5°C/second Maximum

#### Time Maintained Above:

- Temperature (T<sub>L</sub>) 150°C  
 - Time (t<sub>L</sub>) 200 Seconds Maximum

**Peak Temperature (T<sub>P</sub>)** 240°C Maximum

**Target Peak Temperature (T<sub>P</sub> Target)** 240°C Maximum 1 Time / 230°C Maximum 2 Times

**Time within 5°C of actual peak (t<sub>p</sub>)** 10 seconds Maximum 2 Times / 80 seconds Maximum 1 Time

**Ramp-down Rate** 5°C/second Maximum

**Time 25°C to Peak Temperature (t)** N/A

**Moisture Sensitivity Level** Level 1

### Low Temperature Manual Soldering

185°C Maximum for 10 seconds Maximum, 2 times Maximum.

### High Temperature Manual Soldering

260°C Maximum for 5 seconds Maximum, 2 times Maximum.